1.0 SCOPE

This specification documents the detail requirements for space qualified product manufactured on Analog Devices, Inc.'s QML certified line per MIL-PRF-38535 Level V except as modified herein.

The manufacturing flow described in the STANDARD SPACE LEVEL PRODUCTS PROGRAM brochure is to be considered a part of this specification. http://www.analog.com/aerospace

This data sheet specifically details the space grade version of this product. A more detailed operational description and a complete data sheet for commercial product grades can be found at www.analog.com/MUX08

2.0 Part Number. The complete part number(s) of this specification follow:

Part Number	Description
MUX08-913Q	Radiation Tested, 8-channel JFET analog multiplexer

2.1 Package Description: (see figure 1 for terminal connections)

Letter	Descriptive designator	Case Outline (Lead Finish per MIL-PRF-38535)
Q	GDIP1-T16	16-Lead ceramic dual-in-line package (CERDIP)

3.0 Absolute Maximum Ratings. (T_A = 25°C, unless otherwise noted)

Positive supply voltage .... +18V
Negative supply voltage .... -18V
Logic input voltage .... (-4V or V_{EE}) to V_{CC}
Analog input voltage .... V_{EE} - 20V to V_{CC} + 20V
Maximum current through any pin 25mA
Operating Temperature Range................. …………………………………………-55°C to +125°C
Storage temperature range .... -65°C to +150°C
Power dissipation (P_D) 500mW
Lead temperature (soldering, 60 seconds) .... +300°C
Junction temperature (T_J) .... +150°C
Thermal resistance, junction to case (Θ_{JC}) .... See MIL-STD-1835
Thermal resistance, Junction to ambient (Θ_{JA})
     Case Q .... 91°C/W
     Case RC .... 110°C/W

		Package
		Q
Terminal Number	1	A_0
	2	ENABLE
	3	V_{EE}
	4	S1
	5	S2
	6	S3
	7	S4
	8	DRAIN
	9	S8
	10	S7
	11	S6
	12	S5
	13	V_{CC}
	14	GND
	15	A_2
	16	A_1

Figure 1 - Terminal connections.

A2	A1	A0	ENABLE	"On" Channel
X	X	X	L	None
L	L	L	H	1
L	L	H	H	2
L	H	L	H	3
L	H	H	H	4
H	L	L	H	5
H	L	H	H	6
H	H	L	H	7
H	H	H	H	8

Figure 2 - Truth Table

4.0 Electrical Table:

Parameter See notes at end of table	Symbol	Conditions $V_S = \pm15V$ unless otherwise specified		Sub-group	Limit Min	Limit Max	Units
Positive supply current	I_{CC}			1		12	mA
				2, 3		15	
Negative supply current	I_{EE}			1	-3.8		
				2, 3	-5		
Digital input current	I_{IN}	$V_{IN} = 0.4V$ to 15V		1		±10	µA
				2, 3		±20	
Digital "0" enable current	$I_{IN(EN)}$	$V_{IN(EN)} = 0.4V$		1		±10	
				2, 3		±20	
"ON" resistance	R_{ON}	$-10V < V_S < +10V$, $I_S = 200\,\mu A$		1		300	Ω
				2, 3		400	
"ON" resistance change with change in source voltage 1/	$\Delta R_{ON}/\Delta V_S$	$-10V < V_S < +10V$, $I_S = 200\,\mu A$		1		5	%
				2		7	
				3		6	
RON match between switches 4/	$R_{ON\ MATCH}$	$V_S = 0V$, $I_S = 200\,\mu A$		1		15	
				2		20	
				3		18	
Analog voltage range 1/	V_A			1, 2, 3	±10		V
Source current (OFF)	$I_{S(OFF)}$	$V_S = +10V$, $V_D = -10V$ 3/	$V_{IL} = 0.8V$	1, 3		±1	nA
			$V_{IL} = 0.7V$	2		±25	
Drain current (OFF)	$I_{D(OFF)}$		$V_{IL} = 0.8V$	1, 3		±1	
			$V_{IL} = 0.7V$	2		±100	
Leakage current, switch (ON)	$I_{S(ON)} + I_{D(ON)}$	$V_S = V_D = +10V$, $V_{IH} = 2V$ 3/		1, 3		±1	
				2		±100	
Digitial "0" input voltage 1/	V_{IL}			1, 3		0.8	V
				2		0.7	
Digital "1" input voltage 1/	V_{IH}			1, 2, 3	2.0		
Functional testes 2/				1, 2, 3	--	--	
Switching time	t_{PHL} t_{PLH}	$V_{S1} = +10V$, $V_{S8} = -10V$, $R_L = 10M\Omega$, $C_L = 10pF$, see fig. 4 & 5		9		2.1	µS
				10, 11		3.5	
Enable delay "ON"	$t_{ON(EN)}$	$V_{S1} = -10V$, $C_L = 10pF$, $R_L = 1K\Omega$, see fig. 5 & 6		9		2.0	
				10, 11		3.0	
Enable delay "OFF"	$t_{OFF(EN)}$			9		0.4	
				10, 11		1.0	
Break-before-make delay	t_{OPEN}	$V_{S1} = V_{S8} = -1V$, see fig. 5 & 7		9	0.1		

TABLE I NOTES:
1/   Guaranteed, if not tested, to the specified limits
2/   Verified by leakage tests
3/   Conditions applied to leakage tests insure worst case leakages.
4/ $R_{ON\ MATCH}$ specified as a percentage of $R_{AVERAGE}$ where:

$$R_{AVERAGE} = \frac{1}{N} \sum_{i=1}^{N} Ri$$

with N = number of channels, Ri = each channel's "ON" resistance.

4.1 Electrical Test Requirements:

Table II	
Test Requirements	Subgroups (in accordance with MIL-PRF-38535, Table III)
Interim Electrical Parameters	1
Final Electrical Parameters	1, 2, 3, 9 1/ 2/
Group A Test Requirements	1, 2, 3, 9, 10, 11
Group C end-point electrical parameters	1 2/
Group D end-point electrical parameters	1
Group E end-point electrical parameters	1

1/   PDA applies to Subgroup 1 only. Delta limits are excluded from PDA
2/   See table III for delta limits.

4.2 Table III. Burn-in test delta limits.

Table III			
TEST TITLE	ENDPOINT LIMIT	DELTA LIMIT	UNITS
R_{ON}	300	50	Ohm

5.0 Life Test/Burn-In Circuit:
5.1   HTRB is not applicable for this drawing.
5.2   Burn-in is per MIL-STD-883 Method 1015 test condition B.
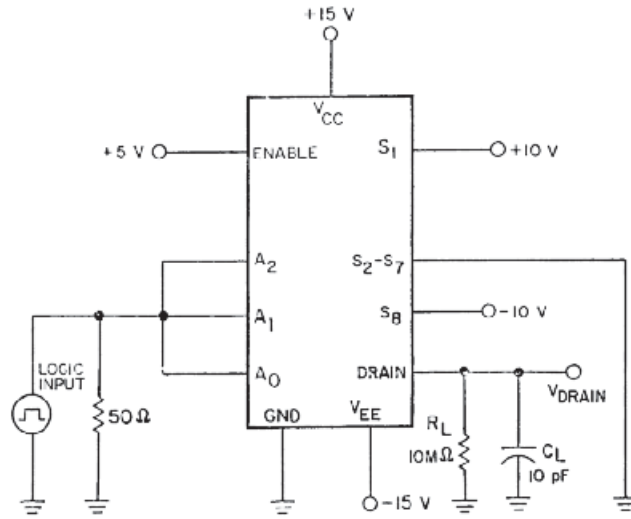5.3   Steady state life test is per MIL-STD-883 Method 1005.
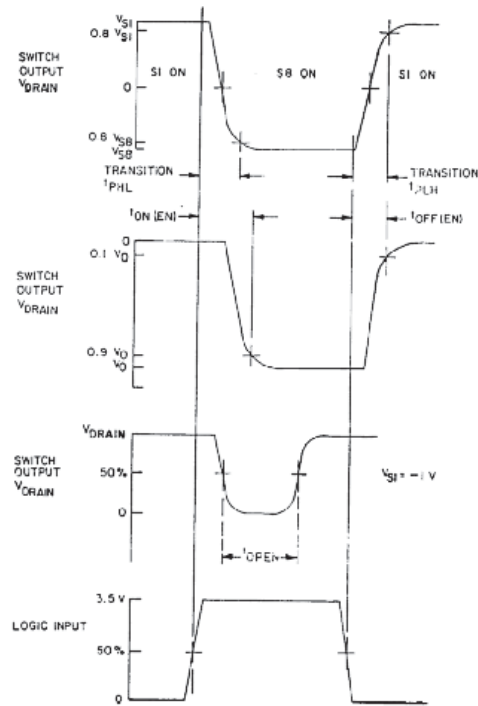
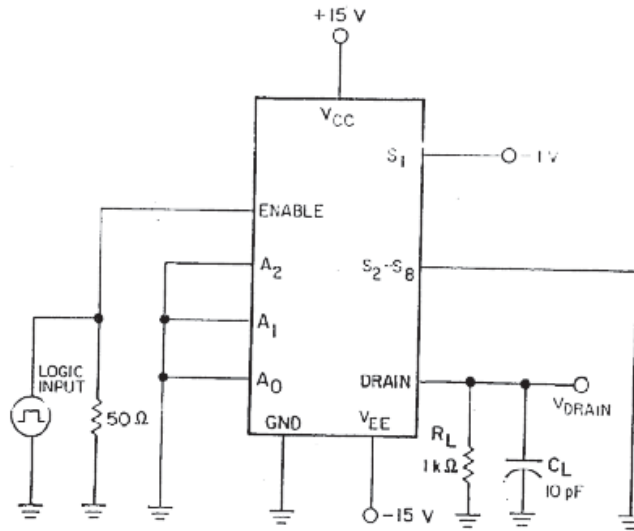Figure 4 - Transition time test circuit

Figure 5 - Switching time waveforms

Figure 6 - Enable delay time test circuit

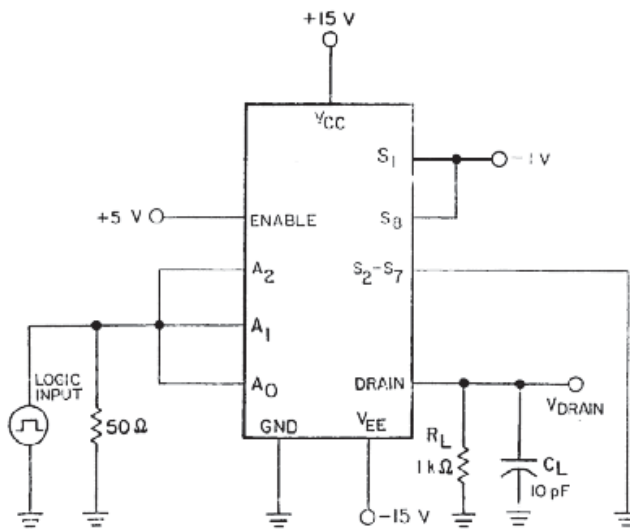Figure 7 - Break-before-make test circuit

Rev	Description of Change	Date
A	Initiate	06-30-2000
B	Update web address	02-18-2002
C	Update web address. Remove Burn-In and rad bias circuits.	05-15-2003
D	Update header/footer & add to 1.0 Scope description	02-22-2008
E	Add Operating Temperature Range -55°C to +125°C to 3.0 Absolute Max Ratings	03-31-2008
F	Remove obsolete part numbers and update ASD to ADI Standard	11-08-2011

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